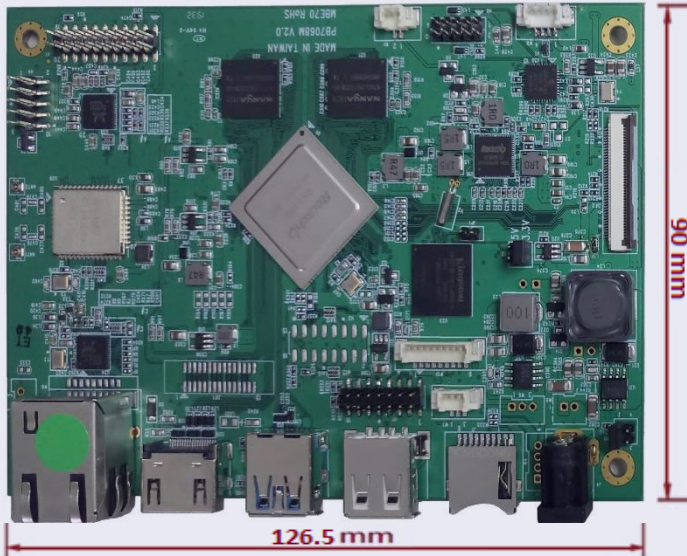


Motherboard with Dual Cortex-A72 + Quad Cortex-A53 core



## Ordering Information

Part number : **MBE70C(E)-abc x y**

• **abc:** The type of Processor

(Dual Core-A72 @2.0Ghz,+ Quad Core-A53 @ 1.5Ghz)

“R39” 0 ~ 70°C.

“K39” -20° ~ 70°C.

• **x:** The DDR3 Memory size on board

“1” 1GB of DDR3.

“2” 2GB of DDR3.

• **y:** The eMMC size on board

“8” 8GB of eMMC.

“F” 16GB of eMMC.

## Features

### • Processor:

- High performance Dual Cortex-A72 @2.0Ghz + Quad Cortex-A53 @ 1.5Ghz

### • System Memory & Storage:

- 1GB /2GB/4GB DDR3-1066 SDRAM onboard
- 8GB/16GB eMMC Flash memory

### • Multi-Media Processor:

- ARM Mail-T860MP4 (GPU), AFBC supported
- Provides OpenGL ES1.1/2.0/3.0/3.1, OpenVG1.1, OpenCL, DX11
- Video Decoder:  
H.264/H.265, 10bit, up to 4Kx2K@60fps,  
VP9, 8bit, up to 4Kx2K@60fps,  
MPEG-4/MPEG-2/VP8 up to 1080p@60fps
- Video Encoder:  
H.264/MVC/VP8 encoders by 1080p@30fps

### • External I/O (On board side):

- 1 x Gigabit Ethernet port
- 1 x HDMI® V2.0, 4Kx2K @60fps, HDCP2.x
- 1 x USB 3.0, type A port
- 2 x USB 2.0, type A port
- 1 x Micro SD/SDHC card slot
- 1 x Power Jack

### • Internal I/O

- eDP 1.3, 2 lane , 1080p@60fps, ZIF
- LCD Backlight control wafer
- PCAP touch panel wafer
- WLAN, 802.11 (a/b/g/n/ac, 2Tx2R) + Bluetooth (4.1 LE)
- USB 2.0 (x 3) expansion header
- Audio Combo Header, (Mic\_in,Line\_out, Spk\_out, HP\_out, SPDIF)
- Keys, DIO extension header
- MIPI-CSI, ZIF connector (option)
- MEMS Combo header (option)
- RS232 console wafer

### • Power supply:

- Adaptor DC12V/ 24V
- PD board for PoE IEEE 802.3at (option)

### • Operation Temperature:

Commercial version: 0°C to 70°C

Industrial version :-20°C to 70°C

### • Operating System:

- Android 6.0/ 7.0
- Linux 4.4.154 \_Debian 9.0 (Stretch)

[www.forenex.com.tw](http://www.forenex.com.tw)

e\_mail: [sales@forenex.com.tw](mailto:sales@forenex.com.tw)